



深圳惠贻华普微电子有限公司

## HP03 系列数字气压传感器模块手动焊接指示

The instruction for hand solder of HP03 series digital pressure sensor modules

### *前言*

### *Preface*

我们向您提供的 HP03 系列数字气压传感器模块，是一款温度敏感电子器件，为确保在后续组装加工过程中，不对模块造成损坏或改变性能参数，请遵从我们的建议，进行焊接操作。

HP03 series digital pressure sensor module is an electronic component sensitive to temperature. In order to ensure that you would not cause unnecessary damages or change the functions to them if possibly processing the modules, please follow the instruction to solder.



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## 焊接方式 *Solder Method*

不建议使用回流焊，推荐使用手动焊接。

**Hand solder is recommended instead of reflow solder.**

## 焊接工具的选择

### *The Selection of Soldering tools*

在我们的焊接试验和客户使用反馈中，我们没有发现使用开放式烙铁（无闭环



温度控制的普通烙铁)，对焊接或产品性能造成明显影响，但基于无铅焊接的品质要求和提高焊接生产率的需要，我们推荐您使用有闭环温度控制的恒温烙铁，并选用合适烙铁头。客户的使用反馈中显示，尺寸粗大的烙铁头会明显降低焊接效率，增加短路

的机会。

According to both our soldering experiment and customers' feedback, we don't find that it results in obvious effect on soldering and products' functions by using open soldering pens(i.e. common soldering pens without closed-loop temperature control). However, considering the requirements of lead-free soldering and its productivity improvement, we suggest that you should use thermostatic soldering pen with closed-loop temperature control and select appropriate solder tip. Please kindly note that big solder tips, according to the feedback from customers, obviously bring about low efficiency of soldering and increase the possibility of short-circuit.

## 焊接材料的选择

### *The Selection of Soldering Materials*

我们向您提供的数字气压传感器模块，是完全符合环保无铅要求的绿色产品，

我们建议您在焊接中使用符合环保要求的无铅焊锡。

我们推荐以下两种合金成份的焊锡，配合免清洗松香

（线芯或外加松香）：

——Sn96.5%/Ag3.0%/Cu0.5%

——Sn96.5%/Ag3.5%



The digital pressure sensor modules we provide are green products in complete accordance with the lead-free requirement; therefore, we suggest you should use environment-friendly lead-free soldering tin. We recommend two alloyed soldering tins as below to match the no-clean rosin(core and additive rosin):

——Sn96.5%/Ag3.0%/Cu0.5%

——Sn96.5%/Ag3.5%

## 焊接条件及注意事项 *Soldering Conditions and Precautions*

如果焊接中具备测量实际焊接温度的条件，我们建议您将实际焊接温度控制在 260℃ 以下；如果您不具备测试实际焊接温度的条件，我们建议您将焊接烙铁的设定温度，设置在 340℃ 以下。

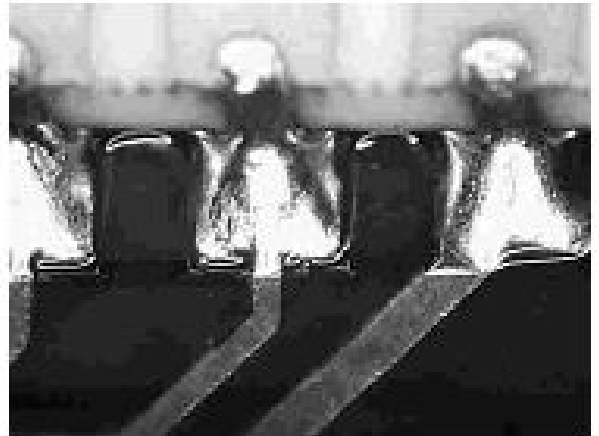
Please keep the practical soldering temperature under 260℃ on the condition that you are able to control the temperature; otherwise, we suggest you should ensure the soldering temperature is less than 340℃.

在焊接操作中，我们提请注意以下事项：

——让熟练的操作员执行焊接任务，缩短焊接时间，降低损坏模块的可能性；

——在使用外加松香时，注意控制松香用量，减少松香和锡渣飞溅；

——为防止飞溅物溅落到封装胶上，金属圈



上贴有保护膜，焊接前请检查模块的保护膜是否完好。

In the course of soldering, please kindly note:

1. Arrange skilled operators to solder in order to shorten soldering time and lessen the fault rate.
2. When using additive rosin, please pay attention to the control of rosin to lessen or avoid rosin and tin splash.
3. The metal ring is protected with a film from the splash. Please check if the protected film is complete and in good condition.



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## 其它

### *Others*

客户应根据生产实际情况，制定符合以上提示的焊接工艺，如有疑问请查询我们的网站，或与技术支持人员联系。

Based on the actual situations, Customers are supposed to carry out soldering technics in line with the above-mentioned instructions. If you have any questions, please refer to our website or contact our technical staff.